

## S2L-SMT 3.50/06/90 3.2SN BK BX

**Weidmüller Interface GmbH & Co. KG**

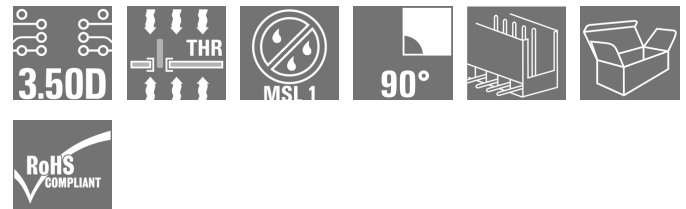
Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com

### Product image



Similar to illustration

High-temperature-resistant, straight, 2-tier pin header for all common soldering methods. Optimized for automatic assembly. Packed in box or tape. 3.2 mm solder pin suitable for reflow and wave soldering. These pin headers can be labelled and coded. (Packaging in tape on request)

### General ordering data

Version	PCB plug-in connector, male header, open side, THT/THR solder connection, 3.50 mm, Number of poles: 6, 90°, Solder pin length (l): 3.2 mm, tinned, black, Box
Order No.	<a href="#">1794370000</a>
Type	S2L-SMT 3.50/06/90 3.2SN BK BX
GTIN (EAN)	4032248231553
Qty.	174 pc(s).
Product data	IEC: 160 V / 10 A UL: 150 V / 10 A
Packaging	Box

Creation date March 25, 2021 9:43:24 AM CET

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**Technical data**
**Dimensions and weights**

Depth	14.2 mm	Depth (inches)	0.559 inch
Height	14 mm	Height (inches)	0.551 inch
Height of lowest version	10.8 mm	Net weight	1.76 g
Width	10.5 mm	Width (inches)	0.413 inch

**System specifications**

Product family	OMNIMATE Signal - series B2L/S2L 3.50 - 2-row	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	3.5 mm
Pitch in inches (P)	0.138 inch	Outgoing elbow	90°
Number of poles	6	Number of solder pins per pole	1
Solder pin length (l)	3.2 mm	Solder pin dimensions	d = 1.0 mm, Octagonal
Solder eyelet hole diameter (D)	1.3 mm	Solder eyelet hole diameter tolerance (D)+	0, 1 mm
Outside diameter of solder pad	2.1 mm	Template aperture diameter	1.9 mm
L1 in mm	7 mm	L1 in inches	0.276 inch
Number of rows	2	Pin series quantity	2
Touch-safe protection acc. to DIN VDE 57 106	Safe from back-of-hand touch	Touch-safe protection acc. to DIN VDE 0470	IP 10
Can be coded	Yes	Plugging force/pole, max.	3 N
Pulling force/pole, max.	6 N		

**Material data**

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIb
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Copper alloy
Contact surface	tinned	Layer structure of solder connection	2...3 µm Ni / 5...7 µm Sn glossy
Layer structure of plug contact	2...5 µm Sn / 1...3 µm Ni	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

**Rated data acc. to IEC**

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	10 A
Rated current, max. number of poles (Tu=20°C)	10 A	Rated current, min. number of poles (Tu=40°C)	9 A
Rated current, max. number of poles (Tu=40°C)	8.5 A	Rated voltage for surge voltage class / pollution degree II/2	160 V
Rated voltage for surge voltage class / pollution degree III/2	125 V	Rated voltage for surge voltage class / pollution degree III/3	50 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	1.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	1.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV	Short-time withstand current resistance	3 x 1s with 77 A

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**Technical data****Rated data acc. to CSA**

Institute (CSA)



Certificate No. (CSA)

200039-1176845

Rated voltage (Use group B / CSA) 150 V

Rated voltage (Use group C / CSA) 50 V

Rated voltage (Use group D / CSA) 150 V

Rated current (Use group B / CSA) 5 A

Rated current (Use group C / CSA) 9.5 A

Rated current (Use group D / CSA) 9.5 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

**Rated data acc. to UL 1059**

Institute (UR)



Certificate No. (UR)

E60693

Rated voltage (Use group B / UL 1059) 150 V

Rated voltage (Use group C / UL 1059) 50 V

Rated current (Use group B / UL 1059) 10 A

Rated current (Use group C / UL 1059) 10 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

**Packing**

Packaging	Box	VPE length	25 mm
VPE width	135 mm	VPE height	350 mm

**Classifications**

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01

**Important note**

IPC conformity

Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

Notes

- Gold-plated contact surfaces on request
- Rated current related to rated cross-section & min. No. of poles.
- Spacing between rows: see hole layout
- Rated current related to rated cross-section & min. No. of poles.
- Diameter of solder eyelet D = 1.3+0.1 mm
- P on drawing = pitch
- Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
- Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months

Creation date March 25, 2021 9:43:24 AM CET

Catalogue status 12.03.2021 / We reserve the right to make technical changes.

**Data sheet****S2L-SMT 3.50/06/90 3.2SN BK BX**

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**Technical data****Approvals**

Approvals



ROHS	Conform
UL File Number Search	E60693

**Downloads**

Approval/Certificate/Document of Conformity	<a href="#">Declaration of the Manufacturer</a>
Engineering Data	<a href="#">STEP</a>

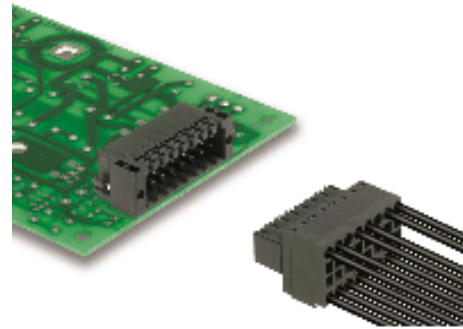
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**Drawings**

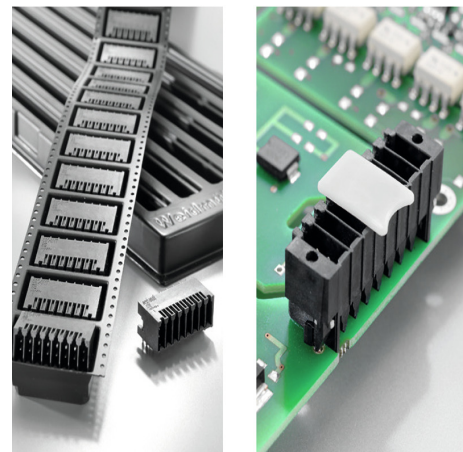
**Example of use**



**Example of use**



**Product benefits**

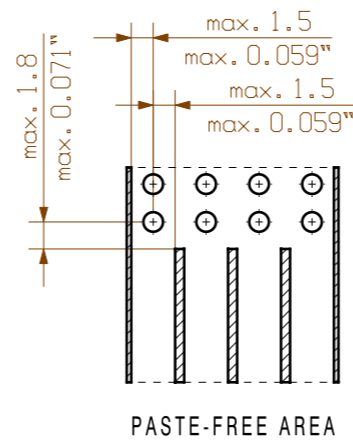
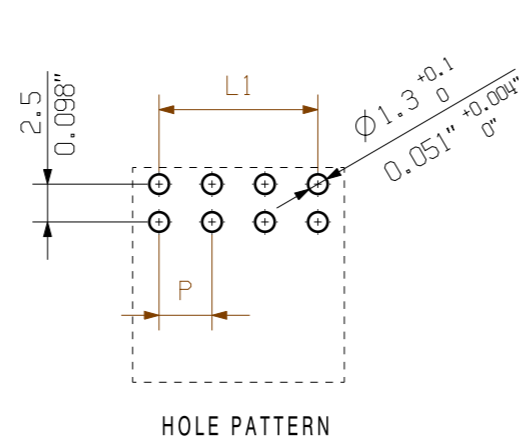
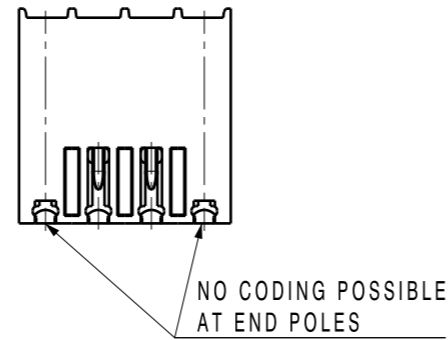
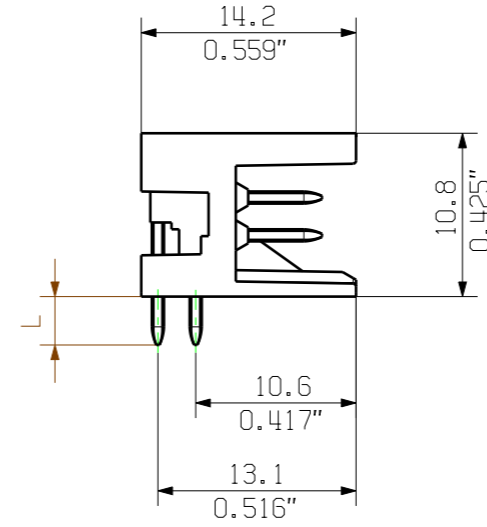
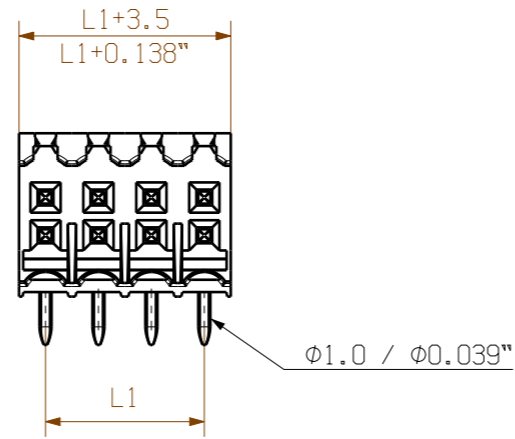


Optimised for the SMT process  
Safe board-to-board connection

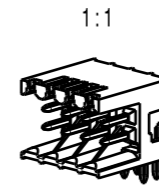
MASSE OHNE TOLERANZ SIND KEINE PRUEFMASSE  
 DIMS. WITHOUT TOLERANCE ARE NOT CONTROL DIMS.

DIE DEUTSCHE VERSION IST VERBINDLICH  
 THE GERMAN VERSION IS BINDING

WEITERGABE SOWIE VERVIELFAELTIGUNG DIESES DOKUMENTS, VERWERTUNG UND MITTEILUNG SEINES INHALTS SIND VERBOTEN, SOWEIT NICHT AUSDRUECKLICH GESTATTET.  
 ZUWIDERHANDLUNGEN VERPFLICHTEN ZU SCHADENERSATZ. ALLE RECHTE FUER DEN FALL DER PATENT-, GEBRAUCHSMUSTER- ODER GESCHMACKSMUSTEREINTRAGUNG VORBEHALTEN.  
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P = PITCH  
 n = NO OF POLES  
 SHOWN: S2L-SMT 3.50/04/90



STIFTLAENGE/ PIN LENGTH L	TOLERANZ/ TOLERANCES
1.5	0
	-0.3
1.8	0
	-0.3
2.3	0
	-0.3
3.2	0
	-0.3
3.5	0
	-0.3

n	L1 [mm]	L1 [inch]
36	59,50	2,343
34	56,00	2,205
32	52,50	2,067
30	49,00	1,929
28	45,50	1,791
26	42,00	1,654
24	38,50	1,516
22	35,00	1,378
20	31,50	1,240
18	28,00	1,102
16	24,50	0,965
14	21,00	0,827
12	17,50	0,689
10	14,00	0,551
8	10,50	0,413
6	7,00	0,276
4	3,50	0,138

For the mounting of PCBs, it should be noted that the rated data relates only to the PCB components alone. The necessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to IEC 664 / VDE 0110. The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

Weidmüller PCB components are tested to the DIN EN 61984 standard, and are valid for its field of application. Provided that the components are used to the intended purpose, all requirements with respect to the occurring of electrical, mechanical, thermic and corrosive stress will be satisfied.

DIN ISO 2768 80058/3 19.01.15 HELIS_MA 01	CAT.NO.: . . . . .	
	MODIFICATION	
SCALE: 2/1 SUPERSEDES: .	DATE: 19.03.2007 NAME: LANG_T	C 32283 26 DRAWING NO. ISSUE NO. SHEET 01 OF 03 SHEETS
	CHECKED: 21.01.2015 NAME: HERTEL_S	
APPROVED	NAME: LANG_T	

## Recommended wave soldering profiles

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 Germany  
 Fon: +49 5231 14-0  
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### Single Wave:



### Double Wave:



### Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

## Recommended reflow soldering profile

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### Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically  $\leq +3\text{K/s}$ . In parallel the solder paste is ‚activated‘. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at  $\geq -6\text{K/s}$  solder is cured. Board and components cool down while avoiding cold cracks.